

XP-002088741

1/1 - (C) WPI / DERWENT
AN - 84-149562 §24!
AP - JP820189496 821028
PR - JP820189496 821028
TI - Synthetic resin thin film prodn. - by forming substrate film then top film, and dissolving substrate with non-solvent for top film
IW - SYNTHETIC RESIN THIN FILM PRODUCE FORMING SUBSTRATE FILM TOP FILM DISSOLVE SUBSTRATE NON SOLVENT TOP FILM
PA - (SHOX) SHOWA ELECTRIC WIRE CO LTD
PN - JP59078816 A 840507 DW8424 003pp
ORD - 1984-05-07
IC - B29D7/00
FS - CPI
DC - A32
AB - J59078816 Synthetic resin films are prep'd. by forming a synthetic resin film on a substrate directly, then forming another synthetic resin film on this, and dripping the whole in a solvent, which dissolves and removes the resin constituting the underlying film but not the resin of the upper layer. Extremely thin films of synthetic resin can be prep'd. easily without use of mercury which pollutes the environment.
- Any material stable under film forming conditions and insoluble to the solvent used can be employed for substrates. Resins used for forming underlying films (and their solvents) are as follows: silicone resin (cresol, xylene, N-methyl-2-pyrrolidone), polyamide resin (ethyl alcohol, cresol), polyester resin (benzene, THF), polyvinyl alcohol resin (water). Resins used for forming upper layer films are polyamide, polyamideimide, polyester imide, polyester or polyurethane resins.(0/0)